


DATA BOOK PACKAGE OUTLINE

<i>CHECK PRINT</i>	
<i>DRAFTSPERSON</i>	<i>DATE</i>
<i>DRAFTING CHECKER</i>	<i>DATE</i>
<i>ENGINEER/REQUESTOR</i>	<i>DATE</i>
<i>APPROVER</i>	<i>DATE</i>

DRAFTSMAN: THANH LEQUANG	DATE: 12/05/2012						
DESIGNER:	DATE:	 TEXAS INSTRUMENTS INC. SEMICONDUCTOR OPERATIONS					
CHECKER: KURT SINCERBOX	DATE: 12/2012						
ENGINEER: DAVID LEWIS	DATE: 12/2012	ePOD, SIL0008A / MicroSiP, 8 PIN					
APPROVED: ERNESTO REY	DATE: 12/2012						
RELEASED: WDM	DATE:						
		<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 15%;">SCALE</td> <td style="width: 15%; text-align: center;">A SIZE</td> <td style="width: 50%; text-align: center; font-size: 24px;">4218258</td> <td style="width: 10%;">REV A</td> <td style="width: 10%;">SHEET 1 / 5</td> </tr> </table>	SCALE	A SIZE	4218258	REV A	SHEET 1 / 5
SCALE	A SIZE	4218258	REV A	SHEET 1 / 5			

CODE IDENTITY
NUMBER
01295

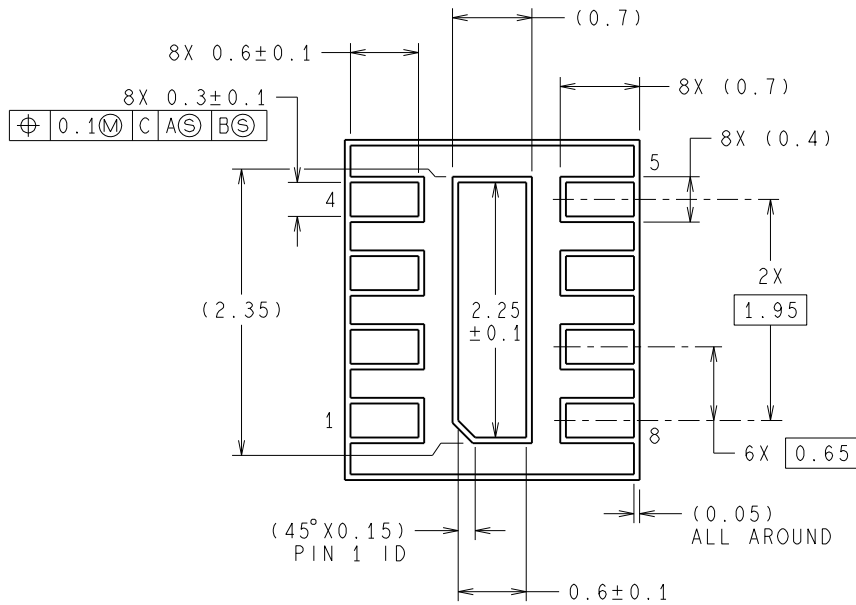
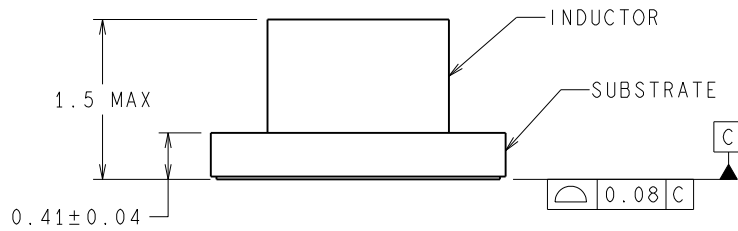
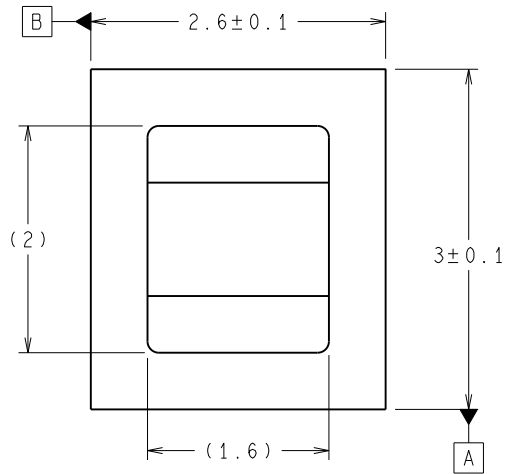


MECHANICAL DATA

SIL0008A

MicroSiP - 1.5mm max height

SYSTEM IN PACKAGE



4218258/A 12/2012

- NOTES:
1. DIMENSIONS ARE IN MILLIMETERS. DIMENSIONS IN PARENTHESIS ARE FOR REFERENCE ONLY.
 2. THIS DRAWING IS SUBJECT TO CHANGE WITHOUT NOTICE.
 3. NO JEDEC REFERENCE AS OF NOVEMBER 2012.
 4. R-uSiP-N8.

SCALE	A
15X	SIZE

4218258

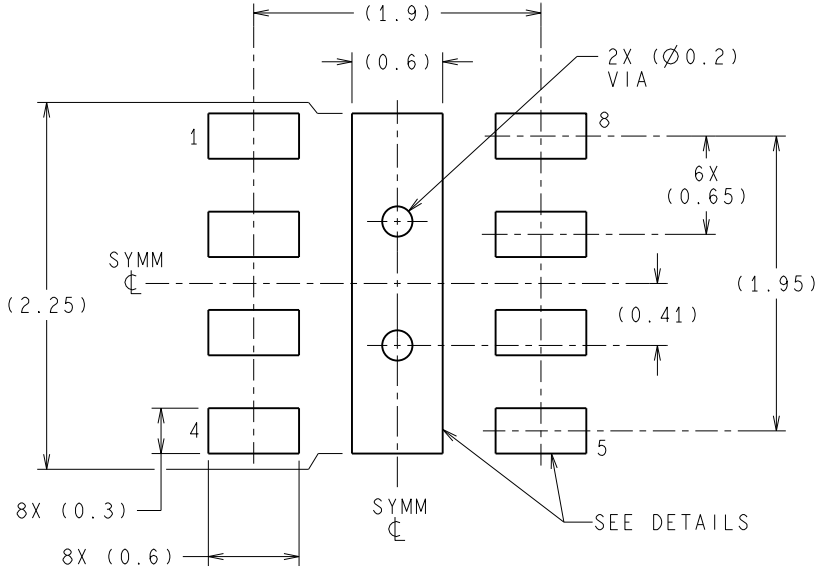
REV	SHEET
A	2 / 5

MECHANICAL DATA

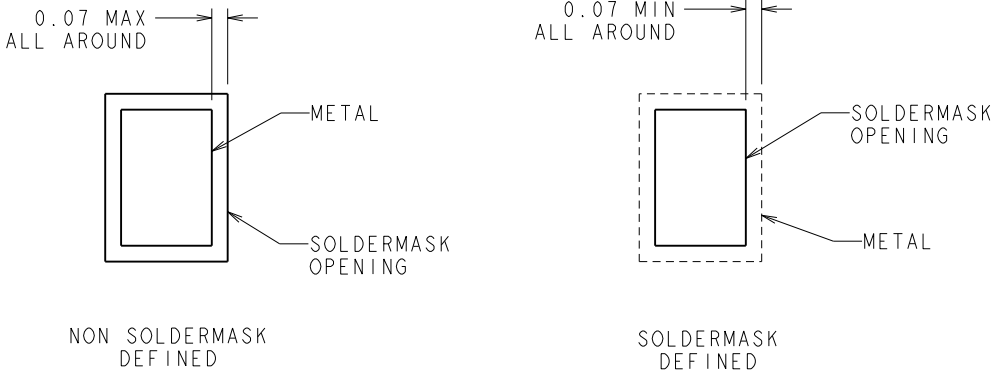
SIL0008A

MicroSiP - 1.5mm max height

SYSTEM IN PACKAGE



RECOMMENDED LAND PATTERN
1:1 RATIO WITH PACKAGE SOLDER PADS



SOLDERMASK DETAILS
NOT TO SCALE

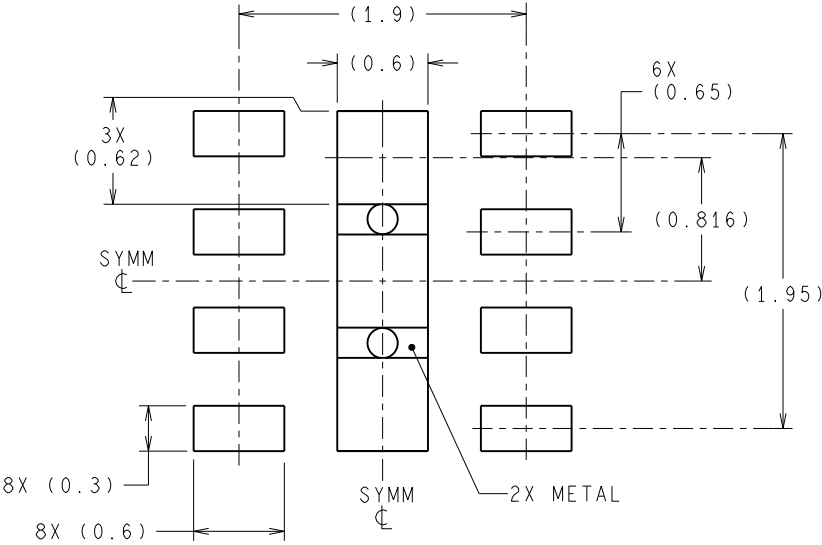
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MECHANICAL DATA

SIL0008A

MicroSiP - 1.5mm max height

SYSTEM IN PACKAGE



RECOMMENDED SOLDERPASTE
EXPOSED PAD
82% PRINTED SOLDER COVERAGE BY AREA

4218258/A 12/2012

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	TBD	12/05/2012	DAVID LEWIS / THANH LEQUANG